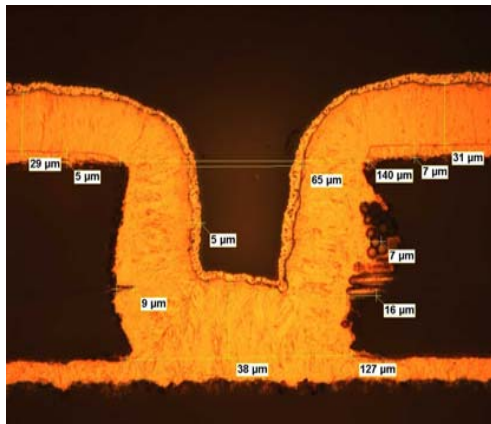


Vertical plating; microvias Multi-Step.

Diameter: 150 μm
Depth: 100 μm



**Bottom; 38 μm Cu
Surface; 31 μm Cu**

TP = 127 %

Diameter: 150 μm
Depth: 100 μm



**Bottom; 40 μm Cu
Surface; 30 μm Cu**

TP = 133 %

**Rectifier:
*D2R- Series***

**Forward CD
*25 ASF***

Reverse CD

***2 Different Reverse
CD used in 3 steps;
"batch-programming".***